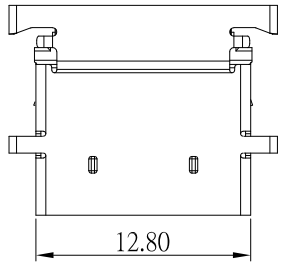


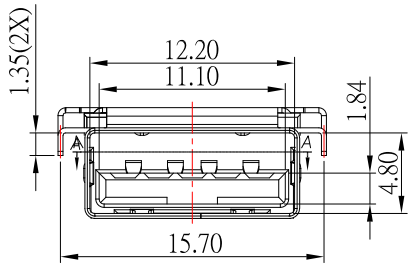
SUA-110E27-30xx-S277

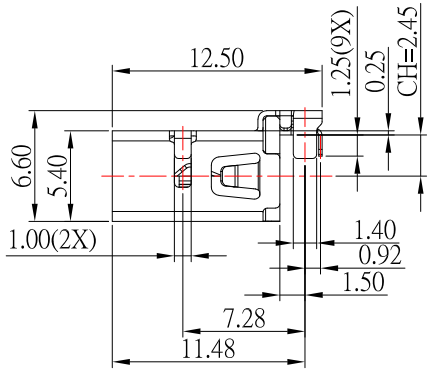
鍍層厚度 :

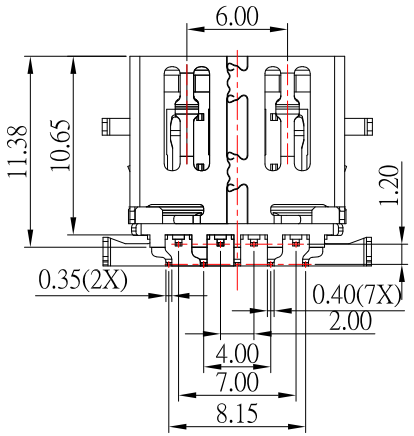
Blank : 1u"
2 : 15u"
3 : 30u"

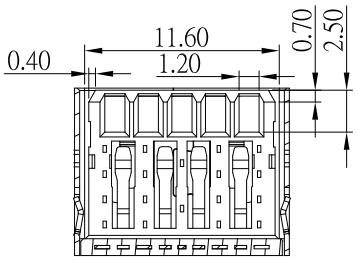
HOUSING :

Blank : Blue
B : BLack





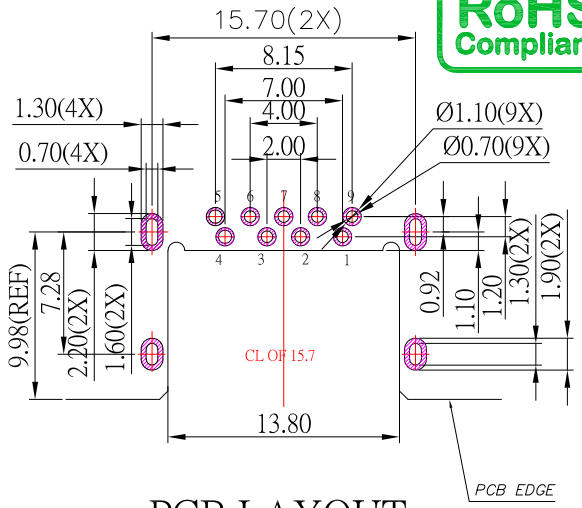




SECTION: A–A

PIN ASSIGNMENTS

PIN NUMBER	SIGNAL NAME	DESCRIPTION
1	VBUS	POWER
2	D–	USB 2.0 DIFFERENTIAL PAIR
3	D+	
4	GND	GROUND FOR POWER RETURN
5	StdA–SSR–	SUPER–SPEED RECEIVER DIFFERENTIAL PAIR
6	StdA–SSR+	
7	GND–DRAIN	GROUND FOR SIGNAL RETURN
8	StdA–SST–	SUPER–SPEED TRANSMITTER DIFFERENTIAL PAIR
9	StdA–SST+	
SHELL	SHIELD	CONNECTOR METAL SHELL



PCB LAYOUT

NOTE:

1.MATERIAL:

1.1 Housing: LCP

1.2 Contact: Phosphor Bronze

1.3 Shell: SUS

2.Finish:

2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall

2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

3.1 Rate: 30V DC , 1.8 A

3.2 insulator Resistance:100MΩ Min

3.3 Dielectric Strength: 100V AC

3.4 Contact Resistance: 30mΩ Max

3.5 Operation Temperature: -55°C ~ +85°C

3.6 Insertion Force: 35 N

3.7 Extraction Force: 10 N

ITEM NO.	DESCRIPTION	DRAWN	DATE

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED : Up to 5 ±0.2; Above 5 ~ 15 ±0.3; Above 15 ~ 30 ±0.4; Above 30 ~ 50 ±0.5; Angle ±0.3°

3RD. ANGEL'S | UNITS | MM

DRAWN BY: Jack Lu	DATE 01/08/26	MAT'L	
CHECKED BY: Jacky Chen	DATE 01/08/26	FINISH	
APPROVED BY: Tony Kao	DATE 01/08/26	SCALE	1 : 1
		SHEET NO.	1 of 1

TITLE	CONNECTOR
MODLE	USB AF 3.0反向無捲邊 DIP 沉板 ,CH2.45 板上H1.45mm
DWG NO.	SUA-110E27-30xx-S277
PART NO.	SUA-110E27-30xx-S277
SIZE	A4
VER	R